

Atty. Dkt. No. AMAT/3577.X1/DSM/BCVD/JW

## D STATES PATENT AND TRADEMARK OFFICE

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In re Application of:

**Judy Huang** 

Serial No.: 09/336,525

Confirmation No.: 7748

Filed:

June 18, 1999

For:

Plasma Treatment to

Enhance Adhesion and to Minimize Oxidation of

Carbon-Containing Layers

**Assistant Commissioner for Patents** Washington, D.C. 20231

Dear Sir:

Group Art Unit: 1762

Examiner:

Padgett, M.

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CERTIFICATE OF MAILING

37 CFR 1.8

I hereby certify that this correspondence is being depusited.

June 17, 2002 with the United States Postal Service as Castal in an envelope addressed to:

Assistants Commissioner for Patents, Washington, D.C. 20231.

Keith M. Tackett

## RESPONSE TO OFFICE ACTION DATED MARCH 15, 2002

In response to the Office Action dated March 15, 2002, having a shortened statutory period for response set to expire on June 15, 2002, please enter the following amendments and reconsider the claims pending in the application for reasons discussed below.

## IN THE CLAIMS:

Please amend the claims as follows:

24. A method of processing a semiconductor substrate, comprising:

depositing a first layer on the semiconductor substrate, the first layer comprising a material selected from the group consisting of organic polymeric materials, αC, αFC, SiCOH, and SiC;

exposing the first layer to a plasma consisting essentially of an inert gas; and depositing a second layer over the first layer.

The method of claim 24, wherein the first layer comprises silicon carbide. 25.